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SST2222A HZG

NPN Medium Power Transistor
(Switching)

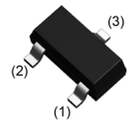
Datasheet

AEC-Q101 Qualified

Parameter	Value
V_{CEO}	40V
I_C	600mA

●Outline

SOT-23

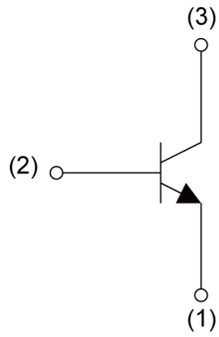


SST3

●Features

1)BV_{CEO}＞40V(I_C=10mA)
2)Complements the SST2907A HZG

●Inner circuit



(1) Emitter
(2) Base
(3) Collector

●Application

AUDIO FREQUENCY SMALL SIGNAL AMPLIFIER

●Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
SST2222A HZG	SOT-23 (SST3)	2924	T116	180	8	3000	R1P

●Absolute maximum ratings (T_a = 25°C)

Parameter	Symbol	Values	Unit
Collector-base voltage	V_{CBO}	75	V
Collector-emitter voltage	V_{CEO}	40	V
Emitter-base voltage	V_{EBO}	6	V
Collector current	I_C	600	mA
Power dissipation	P_D*1	200	mW
Junction temperature	T_j	150	℃
Range of storage temperature	T_{stg}	-55 to +150	℃

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●Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Collector-base breakdown voltage	BV_{CBO}	I_C = 10μA	75	-	-	V
Collector-emitter breakdown voltage	BV_{CEO}	I_C = 10mA	40	-	-	V
Emitter-base breakdown voltage	BV_{EBO}	I_E = 10μA	6	-	-	V
Collector cut-off current	I_{CBO}	V_{CB} = 60V	-	-	100	nA
Emitter cut-off current	I_{EBO}	V_{EB} = 3V	-	-	100	nA
Collector-emitter saturation voltage	$V_{CE(sat)}1$	I_C = 150mA, I_B = 15mA	-	-	300	mV
	$V_{CE(sat)}2$*2	I_C = 500mA, I_B = 50mA	-	-	1.0	V
Base-emitter saturation voltage	$V_{BE(sat)}1$	I_C = 150mA, I_B = 15mA	0.6	-	1.2	V
	$V_{BE(sat)}2$*2	I_C = 500mA, I_B = 50mA	-	-	2.0	V
DC current gain	$h_{FE}1$	V_{CE} = 10V, I_C = 100μA	35	-	-	-
	$h_{FE}2$	V_{CE} = 10V, I_C = 1mA	50	-	-	-
	$h_{FE}3$	V_{CE} = 10V, I_C = 10mA	75	-	-	-
	$h_{FE}4$	V_{CE} = 1V, I_C = 150mA	50	-	-	-
	$h_{FE}5$*2	V_{CE} = 10V, I_C = 150mA	100	-	300	-
	$h_{FE}6$*2	V_{CE} = 10V, I_C = 500mA	40	-	-	-
Transition frequency	f_T*2	V_{CE} = 20V, I_E = -20mA f = 100MHz	300	-	-	MHz
Output capacitance	C_{ob}	V_{CB} = 10V, I_E = 0A f = 100kHz	-	-	8	pF
Input capacitance	C_{ib}	V_{BE} = 500mV f = 100kHz	-	-	25	pF
Delay time	t_d	$V_{CC} \simeq$ 30V, I_C = 150mA I_{B1} = 15mA, R_L = 200Ω $V_{BE(off)}$ = -500mV See test circuit	-	-	10	ns
Rise time	t_r		-	-	25	ns
Storage time	t_{stg}	$V_{CC} \simeq$ 30V I_C = 150mA I_{B1} = 15mA I_{B2} = -15mA, R_L = 200Ω See test circuit	-	-	225	ns
Fall time	t_f		-	-	60	ns

*1 Each terminal mounted on a reference land.

*2 Pulsed

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●Electrical characteristic curves(T_a = 25°C)

Fig.1 Ground Emitter Propagation Characteristics

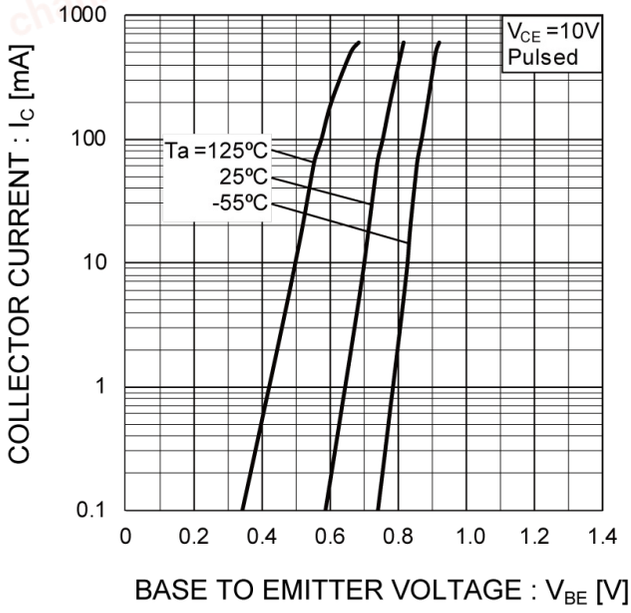


Fig.2 Typical Output Characteristics

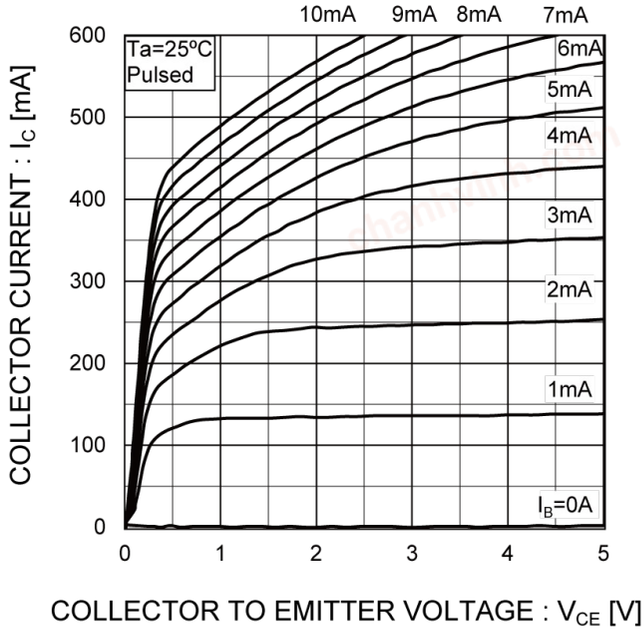


Fig.3 DC Current Gain vs. Collector Current (I)

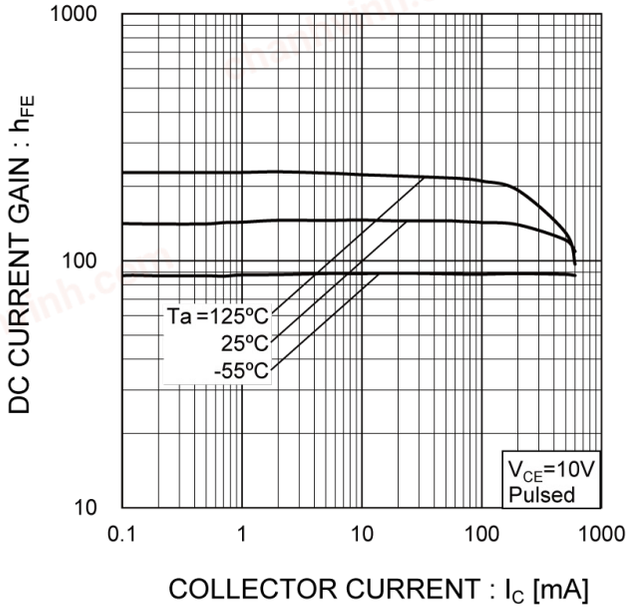
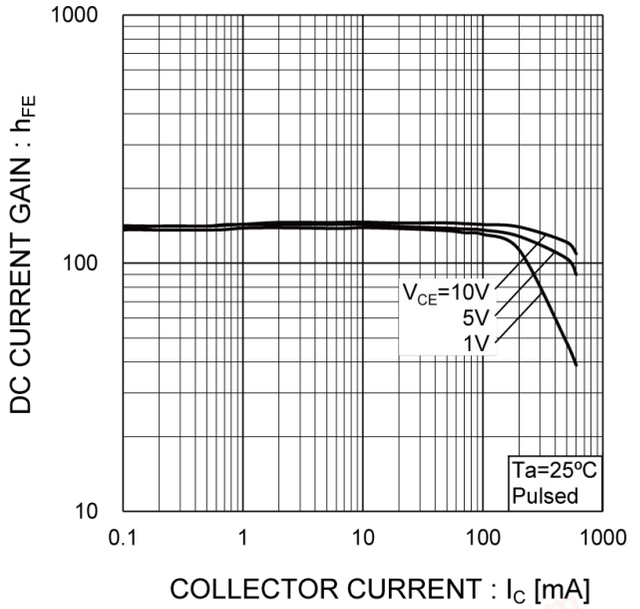


Fig.4 DC Current Gain vs. Collector Current (II)



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●Electrical characteristic curves(T_a = 25°C)

Fig.5 Collector-Emitter Saturation Voltage vs. Collector Current (I)

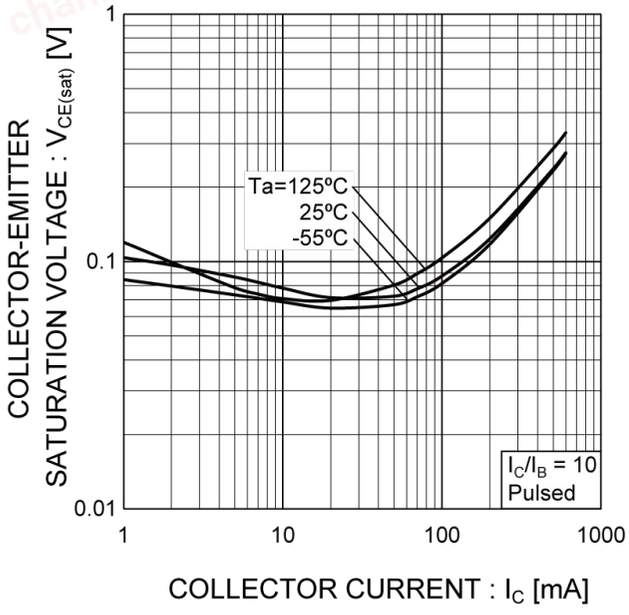


Fig.6 Collector-Emitter Saturation Voltage vs. Collector Current (II)

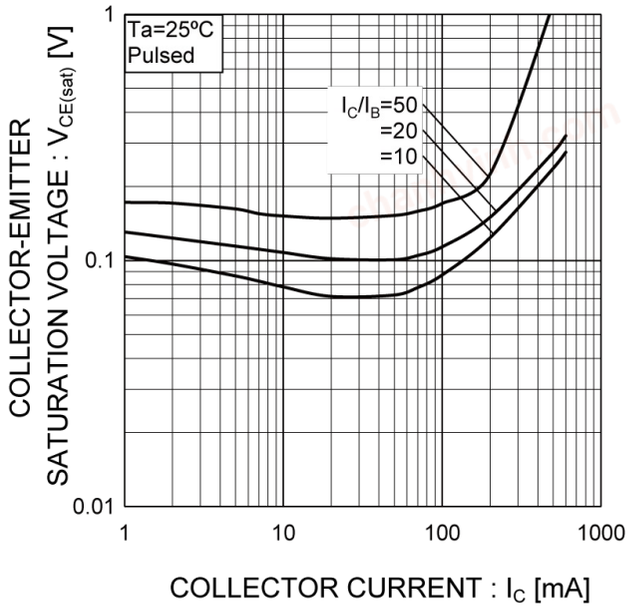


Fig.7 Base-Emitter Saturation Voltage vs. Collector Current

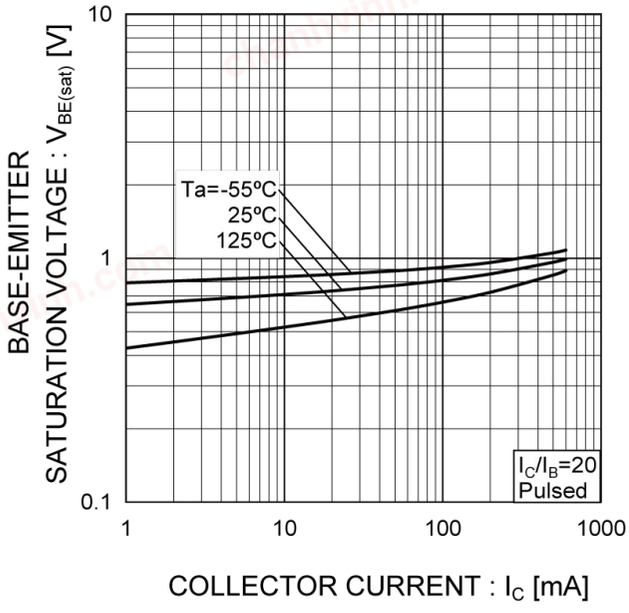
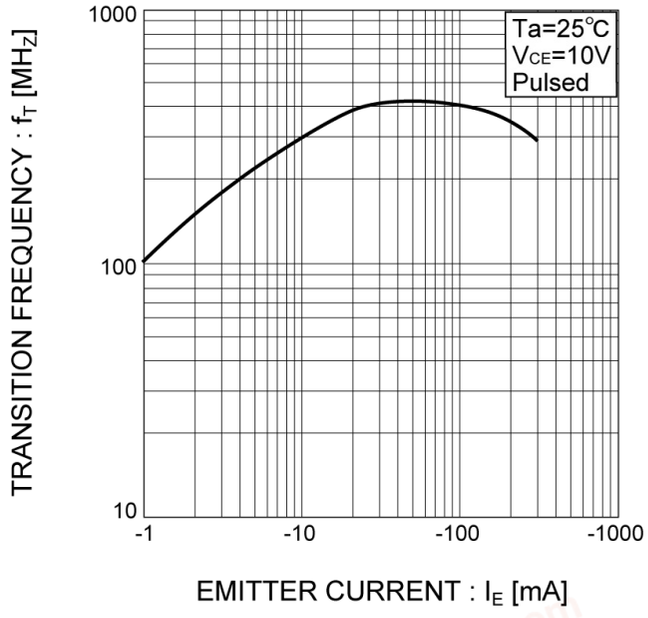


Fig.8 Gain Bandwidth Product vs. Emitter Current



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●Electrical characteristic curves(T_a = 25°C)

Fig.9 Emitter Input Capacitance vs. Emitter-Base Voltage
Collector Output Capacitance vs. Collector-Base Voltage

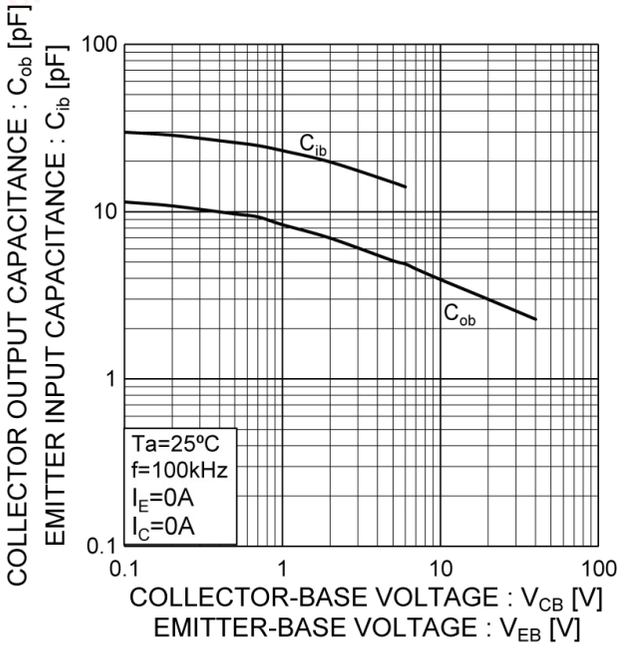
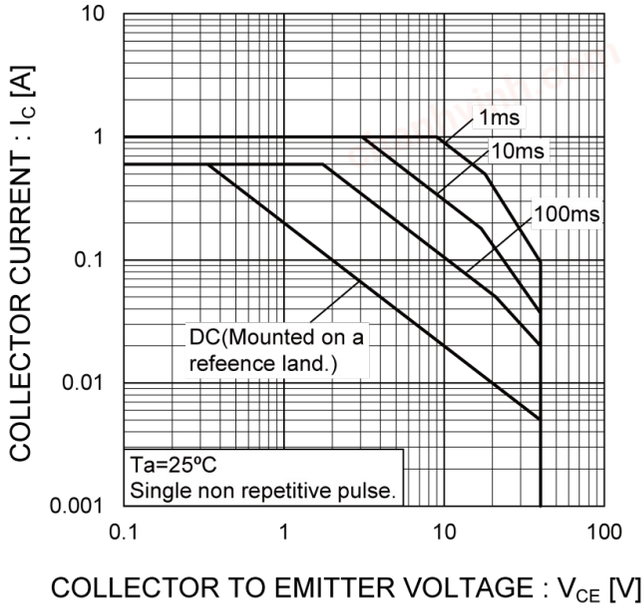
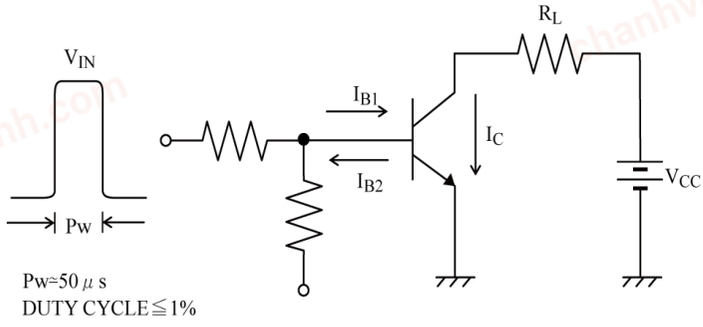
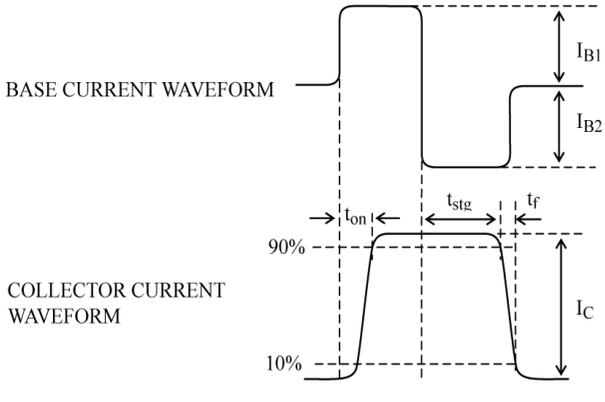


Fig.10 Safe Operating Area



SWITCHING TIME TEST CIRCUIT



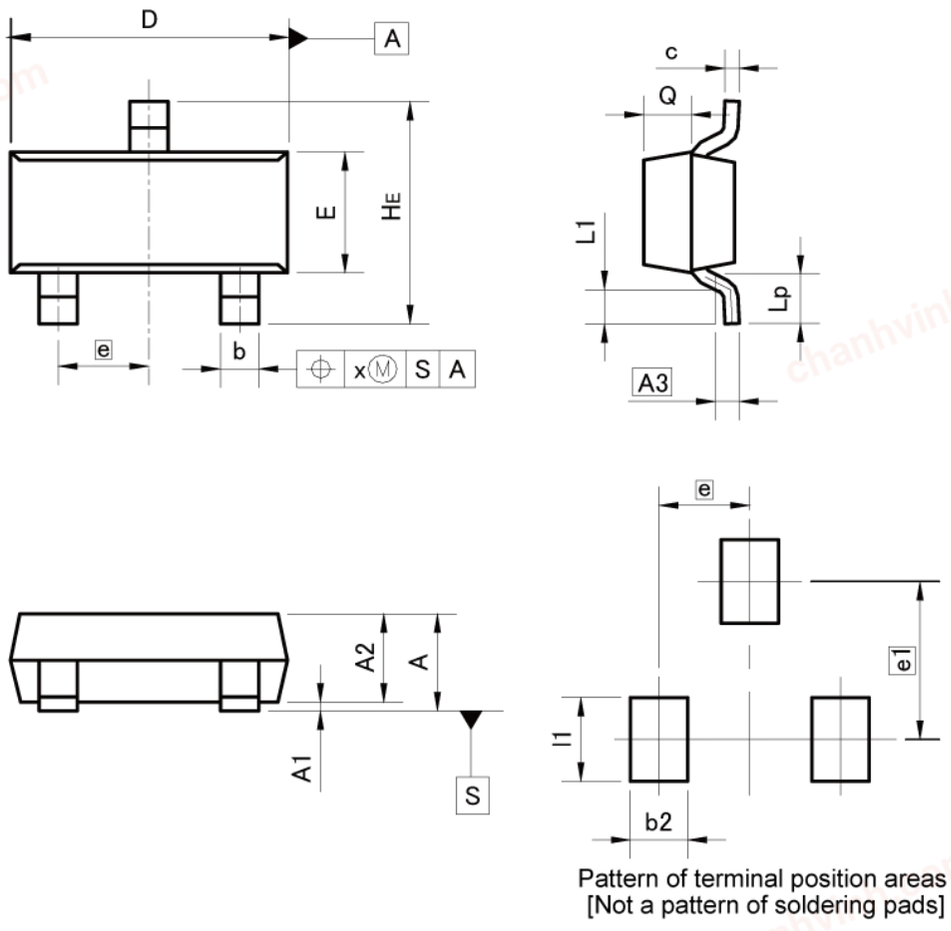


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●Dimensions

SOT-23
(SST3)



Pattern of terminal position areas
[Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.90	1.20	0.035	0.047
A1	0.00	0.10	0.000	0.004
A2	0.85	1.15	0.033	0.045
A3	0.25		0.010	
b	0.35	0.50	0.014	0.020
c	0.09	0.25	0.004	0.010
D	2.70	3.10	0.106	0.122
E	1.20	1.50	0.047	0.059
e	0.95		0.037	
HE	2.20	2.60	0.087	0.102
L1	0.20	–	0.008	–
Lp	0.30	–	0.012	–
Q	0.40	0.60	0.016	0.024
x	–	0.10	–	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	–	0.60	–	0.024
e1	1.70		0.067	
l1	–	0.90	–	0.035

Dimension in mm/inches

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Notice

Precaution on using ROHM Products

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASSⅡb	CLASSⅢ
CLASSⅣ		CLASSⅢ	

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
   [a] Installation of protection circuits or other protective devices to improve system safety
   [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
   [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
   [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
   [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl_2, H_2S, NH_3, SO_2, and NO_2
   [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.

2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
   - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
   - [b] the temperature or humidity exceeds those recommended by ROHM
   - [c] the Products are exposed to direct sunshine or condensation
   - [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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